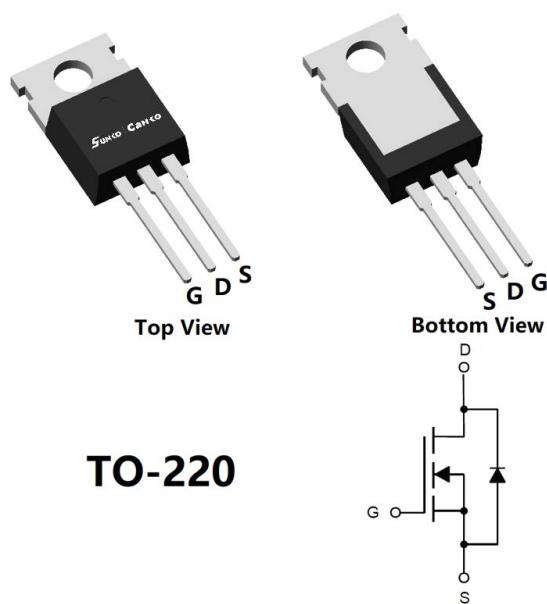


N-Channel Enhancement Mode Field Effect Transistor



Product Summary

- V_{DS} 100V
- I_D 45A
- $R_{DS(on)}$ (at $V_{GS}=10V$) <17 mohm
- 100% EAS Tested
- 100% ∇V_{DS} Tested

General Description

- Low $R_{DS(on)}$ & FOM
- Extremely low switching loss
- Excellent stability and uniformity
- Fast switching and soft recovery
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free

Applications

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

■ Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-source Voltage	V_{DS}	100	V
Gate-source Voltage	V_{GS}	± 20	V
Drain Current	I_D	45	A
		28.5	
Pulsed Drain Current ^A	I_{DM}	220	A
Avalanche energy ^B	E_{AS}	77	mJ
Total Power Dissipation ^C	P_D	100	W
		40	
Junction and Storage Temperature Range	T_J, T_{STG}	-55~+150	°C

■ Thermal resistance

Parameter	Symbol	Typ	Max	Units
Thermal Resistance Junction-to-Ambient ^D	$R_{\theta JA}$	12	15	°C/W
Thermal Resistance Junction-to-Ambient ^D		50	60	
Thermal Resistance Junction-to-Case	$R_{\theta JC}$	1.0	1.25	

■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
SCP45G10B	B1	SCP45G10B	50	/	5000	Tube

■ Electrical Characteristics ($T_j=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	100			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=100\text{V}, V_{\text{GS}}=0\text{V}$			1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{\text{GS}}= \pm 20\text{V}, V_{\text{DS}}=0\text{V}$			± 100	nA
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	2	2.8	4	V
Static Drain-Source On-Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}= 10\text{V}, I_{\text{D}}=20\text{A}$		14	17	$\text{m}\Omega$
Diode Forward Voltage	V_{SD}	$I_{\text{s}}=20\text{A}, V_{\text{GS}}=0\text{V}$			1.3	V
Maximum Body-Diode Continuous Current	I_{s}				45	A
Gate resistance	R_{G}	f= 1 MHz, Open drain		1.2		Ω
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{\text{DS}}=50\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$		1135		pF
Output Capacitance	C_{oss}			399		
Reverse Transfer Capacitance	C_{rss}			18		
Switching Parameters						
Total Gate Charge	Q_{g}	$V_{\text{GS}}=10\text{V}, V_{\text{DS}}=50\text{V}, I_{\text{D}}=25\text{A}$		16		nC
Gate-Source Charge	Q_{gs}			5.6		
Gate-Drain Charge	Q_{gd}			2.4		
Reverse Recovery Charge	Q_{rr}	$I_{\text{F}}=20\text{A}, dI/dt=100\text{A/us}$		42		ns
Reverse Recovery Time	t_{rr}			39.8		
Turn-on Delay Time	$t_{\text{D(on)}}$			39.2		
Turn-on Rise Time	t_{r}	$V_{\text{GS}}=10\text{V}, V_{\text{DD}}=50\text{V}, I_{\text{D}}=25\text{A}$ $R_{\text{GEN}}=2.2\Omega$		11		ns
Turn-off Delay Time	$t_{\text{D(off)}}$			53.2		
Turn-off fall Time	t_{f}			15.8		

- A. Repetitive rating; pulse width limited by max. junction temperature.
- B. $V_{\text{DD}}=50\text{V}, R_{\text{G}}=25\Omega, L=0.5\text{mH}, I_{\text{AS}}=17.5\text{A}.$
- C. P_{d} is based on max. junction temperature, using junction-case thermal resistance.
- D. The value of R_{qJA} is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$. The Power dissipation PDSM is based on $R_{\text{qJA}} t \leq 10\text{s}$ and the maximum allowed junction temperature of 150°C . The value in any given application depends on the user's specific board design.

■ Typical Performance Characteristics

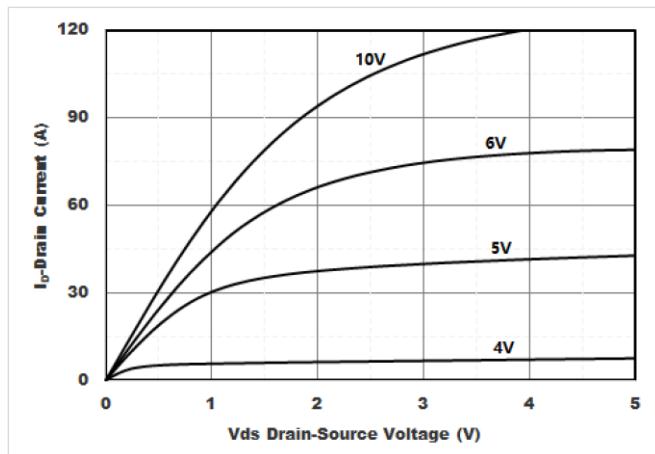


Figure1. Output Characteristics

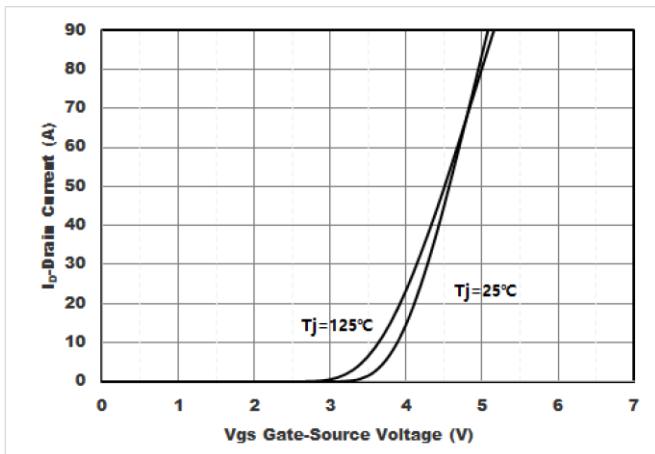


Figure2. Transfer Characteristics

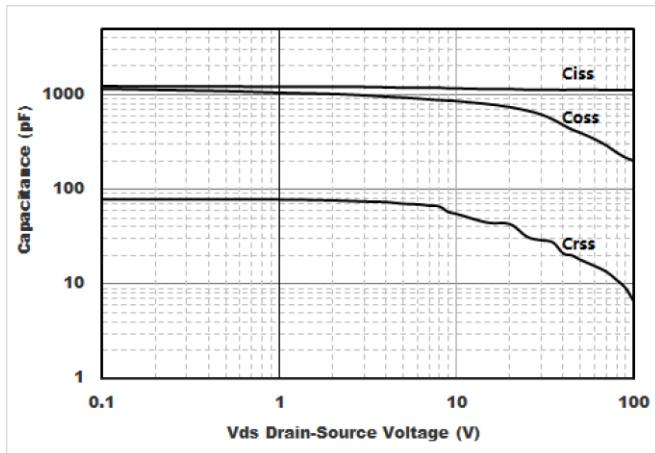


Figure3. Capacitance Characteristics

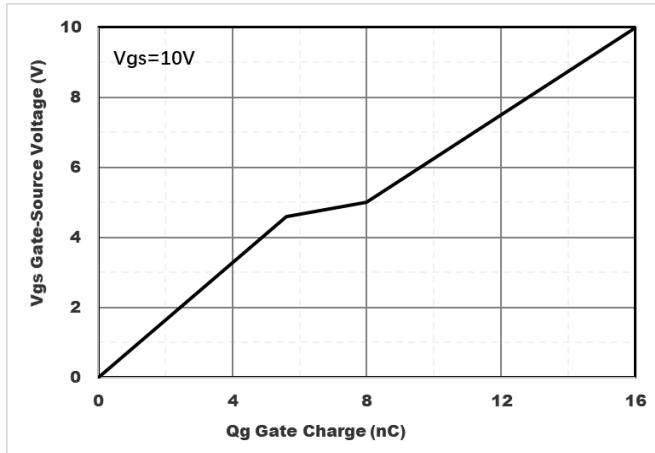


Figure4. Gate Charge

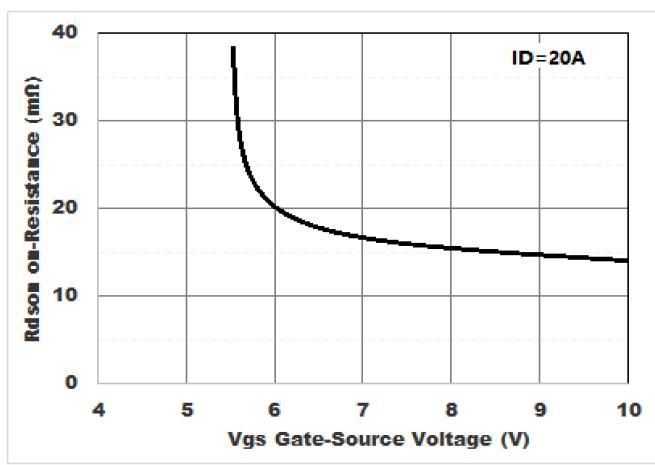


Figure5. : On-Resistance vs. Drain Current and Gate Voltage

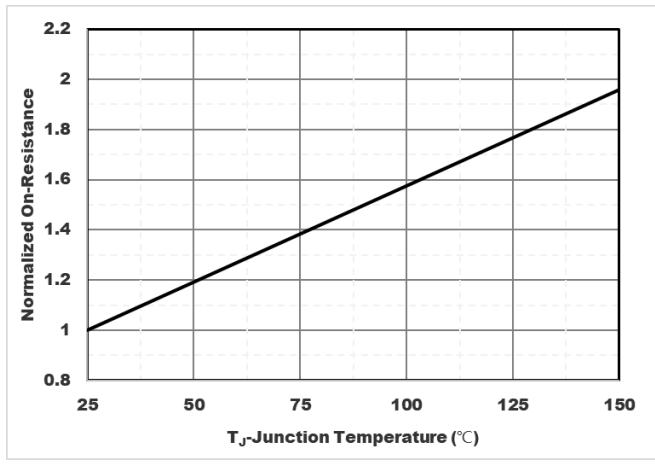


Figure6.Normalized On-Resistance

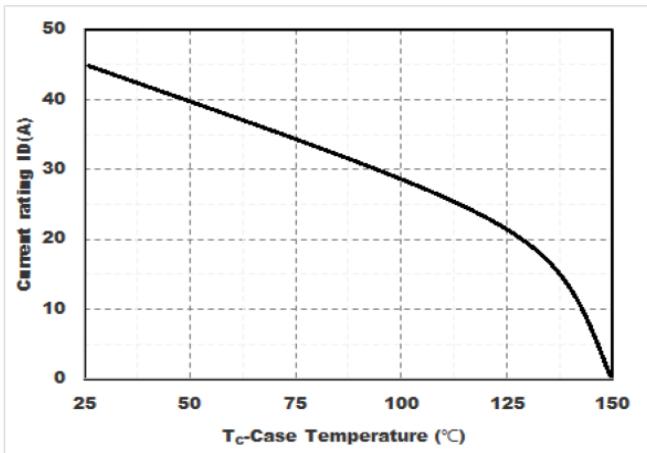


Figure7. Drain current

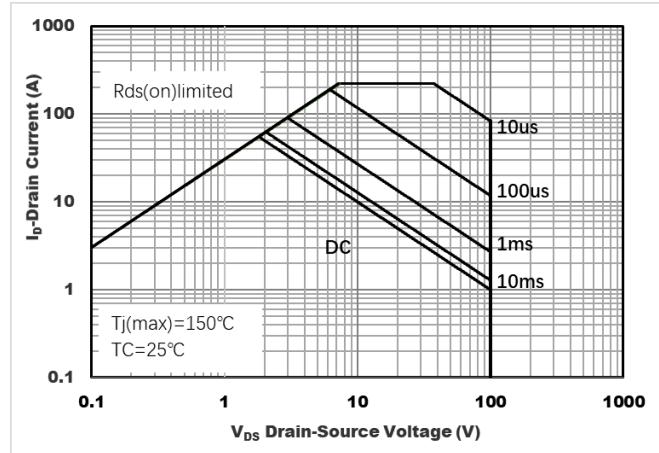


Figure8.Safe Operation Area

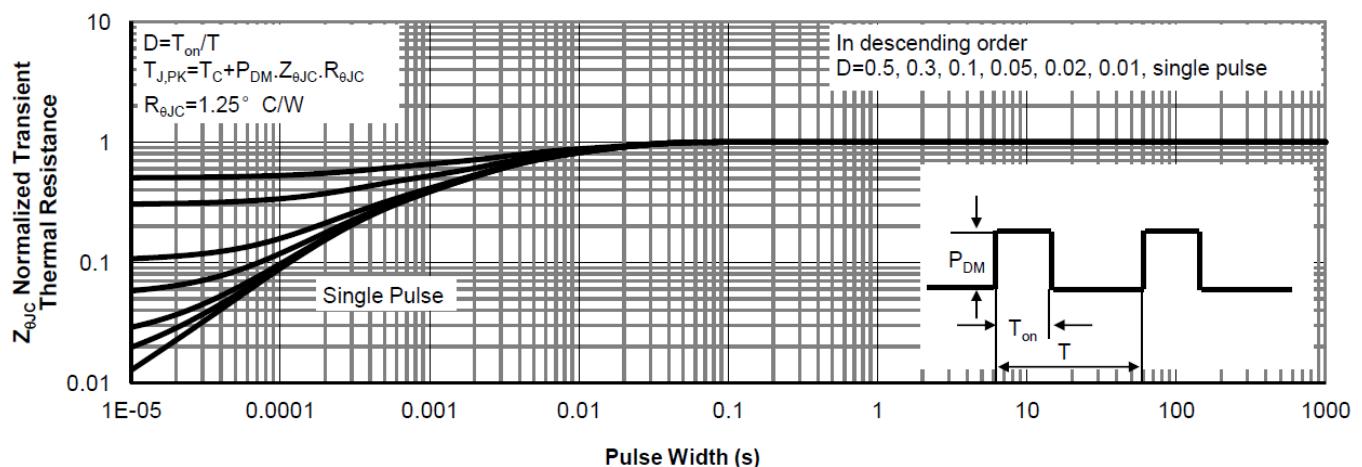
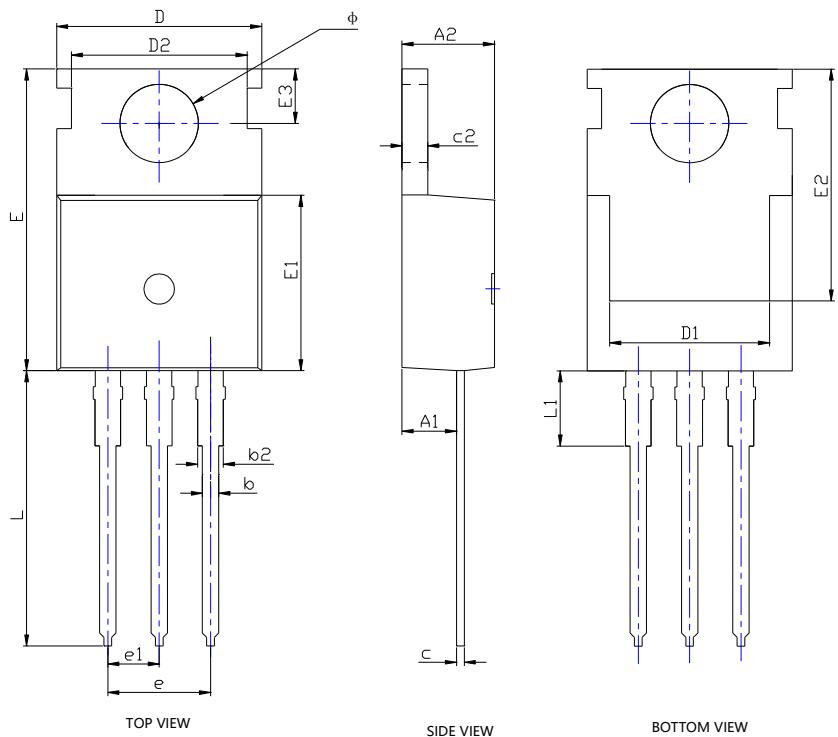


Figure9.Normalized Maximum Transient thermal impedance

■ TO-220AB-C Package information



SYMBOL	DIMENSIONS		Millimeter	
	INCHES		MIN.	MAX.
A1	0.091	0.098	2.300	2.500
A2	0.173	0.181	4.400	4.600
b	0.028	0.035	0.700	0.900
b2	0.049	0.056	1.250	1.420
c	0.018	0.022	0.450	0.550
c2	0.049	0.053	1.250	1.350
D	0.382	0.402	9.700	10.200
D1	0.295	0.331	7.500	8.400
D2	0.335	0.350	8.500	8.900
E	0.602	0.634	15.300	16.100
E1	0.358	0.366	9.100	9.300
E2	0.497	0.525	12.630	13.330
E3	0.108BSC		2.750BSC	
e	0.200BSC		5.080BSC	
e1	0.100BSC		2.540BSC	
L	0.512	0.531	13.000	13.500
L1	---	0.138	---	3.500
Ø	0.140	0.148	3.550	3.750

NOTE:
 1.PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE
 BURRS.
 2.TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.

Disclaimer

The information presented in this document is for reference only. Shanghai Sunco Electronics Co., Ltd. reserves the right to make changes without notice for the specification of the products displayed herein to improve reliability, function or design or otherwise.

The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with equipment or devices which require high level of reliability and the malfunction of which would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices). Russiansunco or anyone on its behalf, assumes no responsibility or liability for any damages resulting from such improper use of sale.

This publication supersedes & replaces all information previously supplied. For additional information, please visit our website <http://www.russiansunco.com>, or consult your nearest Russiansunco's sales office for further assistance.